

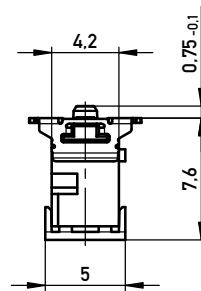
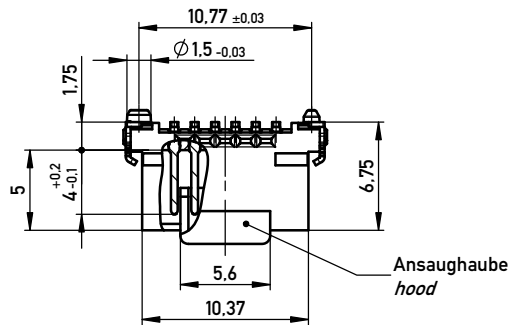
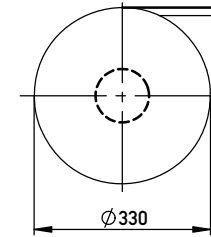
Anforderungsstufe 1
Performance Level 1

Kontaktbereich vergoldet
Mating Area gold plating

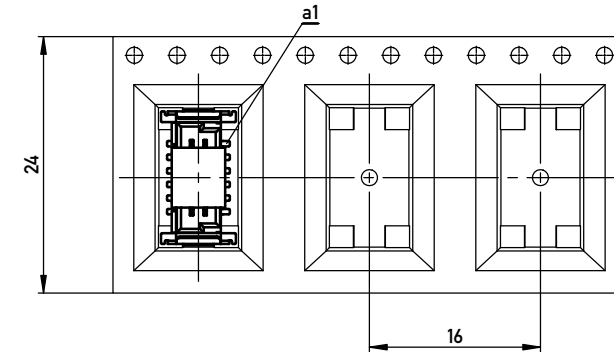
Anschlussbereich verzinkt 4-6 µm
Terminal Area 4-6 µm tin plating

Koplanarität der Anschlüsse ≤ 0,1 mm
Coplanarity Area of Termination ≤ 0,1 mm

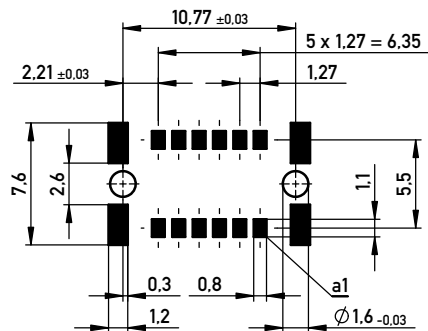
Verpackt im Gurt nach DIN IEC 60286-3
Tape on Reel Packaging according to DIN IEC 60286-3
Verpackungseinheit: 280 Stück
Packaging unit: 280 pcs



Abspulrichtung - Reel off Direction



Leiterplatten-Layout Vorschlag für SMT
PCB-Layout Proposal for SMT



BA 8-13 - 8mm Bauhöhe
type 8-13 - Low Profile

Information:	Tolerances	 All Dimensions in mm	Scale	3:1
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Subject to modification without prior notice. Drawing will not be updated.	Designation		Messertl. SMC-Q 12-SMD-BA8-13 Male SMC-Q 12-SMD-type8-13	
	www.ERNI.com		244836	
e	30.06.2015	Class		SMCQ
Index	Date			I A3

单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)